12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20250710000.1
Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet, BOM options & additional Assembly site option (CDAT, MLA, TFME) for select devices
Change Notification / Sample Request

Date: July 10, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250710000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC257ADR	NULL
SN74LVC157ARGYR	NULL
SN74LVC112APWR	NULL
SN74LVC157ADR	NULL
SN74LVC112ADBR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250710000.1	PCN Date:	July 10, 2025
Title:	Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet, BOM options & additional Assembly site option (CDAT, MLA, TFME) for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	October 08, 2025	Sample requests accepted until:	September 08, 2025*

*Sample requests received after September 08, 2025 will not be supported.

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & additional Assembly site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
FFAB	ASLNONC 10	200mm	RFAB	LBC7	300mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1 device

	Current BOM	Additional BOM
Wire bond diam/type	0.96mil Cu	0.8mil Cu

Group 2 device

	Current site	Additional site
Assembly site	**MLA**	**CDAT**
Wire bond diam/type	0.96mil Cu	0.8mil Cu
Mount compound	4205846	4207123
Mold compound	4208625	4222198

Group 3 device

	Current site		Additional site
Assembly site	**MLA**	**MLA (New)**	**TFME**
Wire bond diam/type	0.96mil Cu	0.8mil Cu	0.8mil Cu
Mount compound	4147858	4147858	SID#A-03
Mold compound	4211471	4211471	SID#R-31
Lead finish	NiPdAu	NiPdAu	Matte Sn

Group 4 device

	Current site			Additional site
Assembly site	**ASESH**	**FMX**	**FMX (New)**	**MLA**
Wire bond diam/type	0.8mil Cu	0.96mil Cu	0.8mil Cu	0.8mil Cu
Mount compound	SID#EY1000	4147858	4147858	4147858

	063			
Mold compound	SID#EN200 0511	4211880	4211880	4211880
Lead finish	Matte Sn	NiPdAu	NiPdAu	NiPdAu

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

TEXAS INSTRUMENTS — SN74LVC112A
SCAS289O – JANUARY 1993 – REVISED JULY 2025

Changes from Revision N (December 2024) to Revision O (July 2025) — **Page**

- Updated 85C *Switching Characteristics* table for V_{CC} = 1.8 and 2.5 V 8
- Updated 125C *Switching Characteristics* table for V_{CC} = 1.8 and 2.5 V 8

TEXAS INSTRUMENTS — SN54LVC157A, SN74LVC157A
SCAS292S – JANUARY 1993 – REVISED DECEMBER 2024

Changes from Revision R (May 2024) to Revision S (December 2024) — **Page**

- Updated RθJA values: D = 73 to 118.1, PW = 108 to 141.8, RGY = 39 to 87.1; Updated D, PW, and RGY packages for RθJC(top), RθJB, ΨJT, ΨJB, and RθJC(bot), all values in °C/W 5

TEXAS INSTRUMENTS — SN54LVC257A, SN74LVC257A
SCAS294Q – JANUARY 1993 – REVISED DECEMBER 2024

Changes from Revision P (May 2024) to Revision Q (December 2024) — **Page**

- Updated RθJA values: D = 73 to 118.1, PW = 108 to 141.8, RGY = 39 to 87.1; Updated D, PW, and RGY packages for RθJC(top), RθJB, ΨJT, ΨJB, and RθJC(bot), all values in °C/W 5

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74LVC112A	SCAS289N	**SCAS289O**	http://www.ti.com/product/SN74LVC112A
SN74LVC157A	SCAS292R	**SCAS292S**	http://www.ti.com/product/SN74LVC157A
SN54LVC257A	SCAS294P	**SCAS294Q**	http://www.ti.com/product/SN74LVC257A

Qual details are provided in the Qual Data Section.
Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising

RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A, B, J	**A**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASESH	ASH	CHN	Shanghai
TI Mexico	MEX	MEX	Aguascalientes
TFME	**NFM**	**CHN**	**Chongchuan**
TI Chengdu	**CDA**	**CHN**	**Chengdu**
TI Malaysia	**MLA**	**MYS**	**Kuala Lumpur**

Sample product shipping label (not actual product label):

Group 1 Product Affected: (Fab, Die rev, BOM update)

SN74LVC112ADBR	SN74LVC112ANSR.A	SN74LVC112APWRG4.B
SN74LVC112ADBR.A	SN74LVC112ANSR.B	SN74LVC257APWRG4
SN74LVC112ADBR.B	SN74LVC112APWRG4	SN74LVC257APWRG4.B
SN74LVC112ANSR	SN74LVC112APWRG4.A	

Group 2 Product Affected: (Fab, Die rev, Assembly site)

SN74LVC157ARGYR	SN74LVC157ARGYR.B	SN74LVC257ARGYR.A
SN74LVC157ARGYR.A	SN74LVC257ARGYR	SN74LVC257ARGYR.B

Group 3 Product Affected: (Fab, Die rev, Assembly site, BOM update)

SN74LVC112APWR	SN74LVC112APWR.A	SN74LVC112APWR.B

Group 4 Product Affected: (Fab, Die rev, Assembly site, BOM update)

SN74LVC112ADR	SN74LVC157ADR.B	SN74LVC257ADR
SN74LVC112ADR.A	SN74LVC157ADRG4	SN74LVC257ADR.A
SN74LVC112ADR.B	SN74LVC157ADRE4	SN74LVC257ADR.B
SN74LVC157ADR	SN74LVC157ADRG4.A	SN74LVC257ADRG4
SN74LVC157ADR.A	SN74LVC157ADRG4.B	

Group 1
SOP Qualification Report

Approve Date 09-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC112ANSR	QBS Reference: SN3257QDYYRQ1	QBS Reference: SN74LV14ANSR	QBS Reference: SN74LVC8T245NSR	QBS Reference: SN74LVC112APWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	1/77/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	1/77/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	1/76/0	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	1/76/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	1/3/0	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	1/30/0	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC112ANSR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-025

Group 1
SSOP Qualification Report
Approve Date 28-MAY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC112ADBR	QBS Reference: SN3257QDYYRQ1	QBS Reference: SRC4190IDB	QBS Reference: GD75232DBR	QBS Reference: SN74LVC165ADRQ1	QBS Reference: SN74LVC112APWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	1/77/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	1/77/0	1/45/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	1/77/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	1/10/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	1/3/0	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	1/30/0	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC112ADBR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-024

Group 1
TSSOP Qualification Report

Approve Date 09-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC112APWR	QBS Reference: SN3257QDYYRQ1	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74LVC2G100PWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	1/10/0
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC112APWR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2409-084

Group 2
Qualification Report
Approve Date 15-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC157ARGYR	**QBS Reference: SN3257QDYYRQ1**	QBS Reference: SN74HCS595QBQBRQ1	**QBS Reference: TXV0108QWRGYRQ1**	QBS Reference: SN74LVC2G100BQBR	**QBS Reference: SN74LVC157AQPWRQ1**	QBS Reference: SN74LVC157AWBQBRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	1/77/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	1/45/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	1/77/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-	-
SD	C3	PB Solderability	8 Hours Steam Age	-	-	-	1/22/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	1/15/0	-	-	1/15/0
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	1/22/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	1/22/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	1/10/0	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-	-	-	-
ESD	E2	ESD CDM	-	2000 Volts	-	-	1/3/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	1/3/0	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	1/3/0	-	1/3/0	-
ESD	E2	ESD HBM	-	7000 Volts	-	-	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/6/0	1/6/0	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	3/90/0	-	1/30/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC157ARGYR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-023

Group 3
MLA Qualification Report
Approve Date 09-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC112APWR	QBS Reference: SN3257QDYYRQ1	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74LVC2G100PWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	1/10/0
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC112APWR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2409-084

Group 3
TFME Qualification Report
Approve Date 09-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC112APWR	QBS Reference: SN3257QDYYRQ1	QBS Reference: SN74HCS74PWR	QBS Reference: SN74LVC157APWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB Solder;	-	-	-	3/66/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	3/66/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	3/9/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC112APWR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2409-109

Group 4
MLA Qualification Report
Approve Date 09-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC157ADR	**Qual Device: SN74LVC112ADR**	QBS Reference: SN3257QDYYRQ1	**QBS Reference: SN74HCS74QDRQ1**	QBS Reference: SN74LVC157APWR	**QBS Reference: SN74LVC112APWR**
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/135/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	1/77/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	3/45/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	3/45/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	1/3/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/6/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC157ADR is qualified at MSL1 260C
Qual Device SN74LVC112ADR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-026

Group 4
FMX Qualification Report
Approve Date 09-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC157ADR	**Qual Device: SN74LVC112ADR**	QBS Reference: SN3257QDYYRQ1	**QBS Reference: SN74LVC11ADRQ1**	QBS Reference: SN74LVC132ADRQ1	**QBS Reference: SN74LVC74ADRQ1**	QBS Reference: SN74LVC157APWR	**QBS Reference: SN74LVC112APWR**	QBS Reference: SN74LVC165ADR	QBS Reference: SN74LVC158ADR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	1/45/0	1/45/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	1/77/0	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	-	-	1/22/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	1/10/0	1/10/0	1/10/0	-	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	-	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	1/3/0	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/3/0	-	-	1/3/0	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-	-	1/30/0	1/30/0	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	2/60/0	1/30/0	1/30/0	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC157ADR is qualified at MSL1 260C
Qual Device SN74LVC112ADR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2408-027

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